

# PATENT ABSTRACTS OF JAPAN

(11)Publication number : **59-019671**

(43)Date of publication of application : **01.02.1984**

(51)Int.Cl.

**B24B 37/02**  
**H01L 21/304**

(21)Application number : **57-128251**

(71)Applicant : **DISCO ABRASIVE SYS LTD**

(22)Date of filing : **22.07.1982**

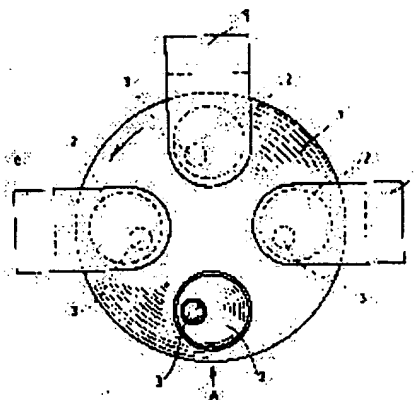
(72)Inventor : **SEKIYA SHINJI**  
**MORI TOSHIYUKI**

## (54) POLISHING DEVICE

(57)Abstract:

**PURPOSE:** To enable all polishing operations to be carried out with a single machine body by arranging intermittently rough finish, medium finish and final finish stations on a track on which a wafer turns around.

**CONSTITUTION:** On a circular line with the same radius of an index table 1 in the same machine body are provided a plurality of rotary tables 2 rotatable together with the table 1 and on their own axes. On the respective rotary tables 2 are provided chuck tables 3 rotatable along the same circular line together with the rotary tables 2 and rotatable on its own axes and provided on the surface with chuck tables 3 having a work adsorbing function. Above this index table 1 are provided respective stations 4, 5, 6 for performing separately rough, medium and final finish polishing on the same circular line as the rotary table 2. In the respective stations 4, 5, 6 are heads which are vertically moved and rotated by air cylinders and having respectively polishing pads.



## LEGAL STATUS

[Date of request for examination]

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number]

[Date of registration]

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's  
decision of rejection]

[Date of extinction of right]

Copyright (C); 1998,2003 Japan Patent Office